



BF861A; BF861B; BF861C

N-channel junction FETs

Rev. 5 — 15 September 2011

Product data sheet

1. Product profile

1.1 General description

N-channel symmetrical junction field effect transistors in a SOT23 package.

CAUTION



The device is supplied in an antistatic package. The gate-source input must be protected against static discharge during transport or handling.

1.2 Features and benefits

- High transfer admittance
- Low feedback capacitance
- Low input capacitance
- Low noise.

1.3 Applications

- Preamplifiers for AM tuners in car radios.

1.4 Quick reference data

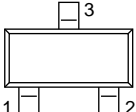

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)		-	-	25	V
I_{DSS}	drain current					
	BF861A	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	2	-	6.5	mA
	BF861B	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	6	-	15	mA
	BF861C	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	12	-	25	mA
P_{tot}	total power dissipation	up to $T_{amb} = 25\text{ °C}$	-	-	250	mW
$ y_{fs} $	forward transfer admittance;					
	BF861A	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	12	-	20	mS
	BF861B	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	16	-	25	mS
	BF861C	$V_{GS} = 0\text{ V}; V_{DS} = 8\text{ V}$	20	-	30	mS
C_{iss}	input capacitance	$f = 1\text{ MHz}$	-	-	10	pF
C_{rss}	reverse transfer capacitance	$f = 1\text{ MHz}$	-	-	2.7	pF



2. Pinning information

Table 2. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	source		 sym053
2	drain		
3	gate		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BF861A	-	plastic surface mounted package; 3 leads	SOT23
BF861B	-	plastic surface mounted package; 3 leads	SOT23
BF861C	-	plastic surface mounted package; 3 leads	SOT23

4. Marking

Table 4. Marking codes

Type number	Marking code ^[1]
BF861A	28*
BF861B	29*
BF861C	30*

[1] * = p: Made in Hong Kong.
 * = t: Made in Malaysia.
 * = W: Made in China.

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)		-	25	V
V_{GSO}	gate-source voltage	open drain	-	25	V
V_{DGO}	drain-gate voltage (DC)	open source	-	25	V
I_G	forward gate current (DC)		-	10	mA
P_{tot}	total power dissipation	up to $T_{amb} = 25\text{ °C}$ ^[1]	-	250	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	operating junction temperature		-	150	°C

[1] Device mounted on an FR4 printed-circuit board.

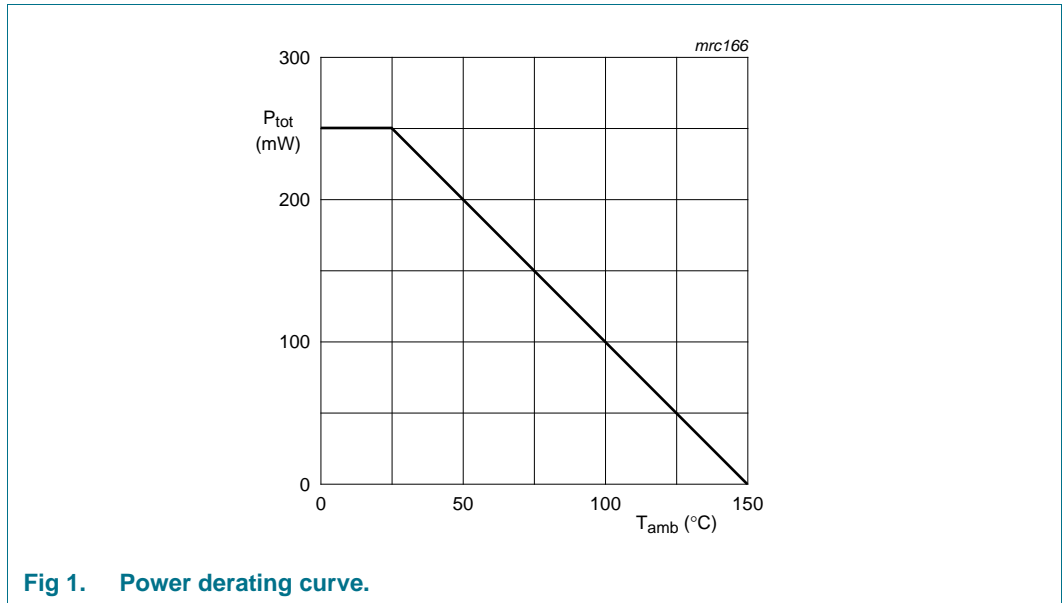


Fig 1. Power derating curve.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Typ	Unit
R _{th(j-a)}	thermal resistance from junction to ambient		[1] 500	K/W

[1] Device mounted on an FR4 printed-circuit board.

7. Characteristics

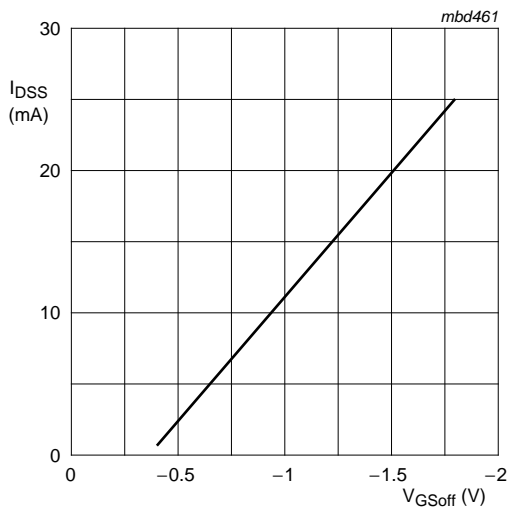
Table 7. Characteristics

T_j = 25 °C; V_{DS} = 8 V; V_{GS} = 0 V unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit	
V _{(BR)GSS}	gate-source breakdown voltage	I _G = -1 μA	-25	-	-	V	
V _{GSoff}	gate-source cut-off voltage	BF861A	I _D = 1 μA	-0.2	-	-1	V
		BF861B	I _D = 1 μA	-0.5	-	-1.5	V
		BF861C	I _D = 1 μA	-0.8	-	-2	V
V _{GSS}	gate-source forward voltage	V _{DS} = 0 V; I _G = 1 mA	-	-	1	V	
I _{DSS}	drain current	BF861A		2	-	6.5	mA
		BF861B		6	-	15	mA
		BF861C		12	-	25	mA
I _{GSS}	gate cut-off current	V _{GS} = -20 V; V _{DS} = 0 V	-	-	-1	nA	

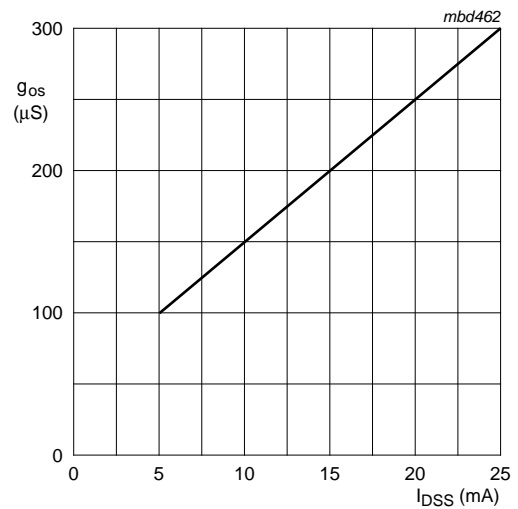
Table 7. Characteristics ...continued
 $T_j = 25\text{ }^\circ\text{C}$; $V_{DS} = 8\text{ V}$; $V_{GS} = 0\text{ V}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$ y_{fs} $	forward transfer admittance					
	BF861A		12	-	20	mS
	BF861B		16	-	25	mS
	BF861C		20	-	30	mS
g_{os}	common source output conductance					
	BF861A		-	-	200	μS
	BF861B		-	-	250	μS
	BF861C		-	-	300	μS
C_{iss}	input capacitance	$f = 1\text{ MHz}$	-	-	10	pF
C_{rss}	reverse transfer capacitance	$f = 1\text{ MHz}$	-	2.1	2.7	pF
V_n/\sqrt{B}	equivalent input noise voltage	$V_{GS} = 0\text{ V}$; $f = 1\text{ MHz}$	-	1.5	-	nV/ $\sqrt{\text{Hz}}$



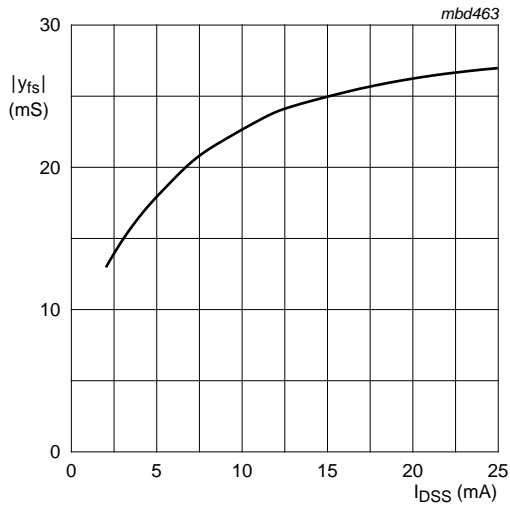
$V_{DS} = 8\text{ V}$.

Fig 2. Drain current as a function of gate-source cut-off voltage; typical values.



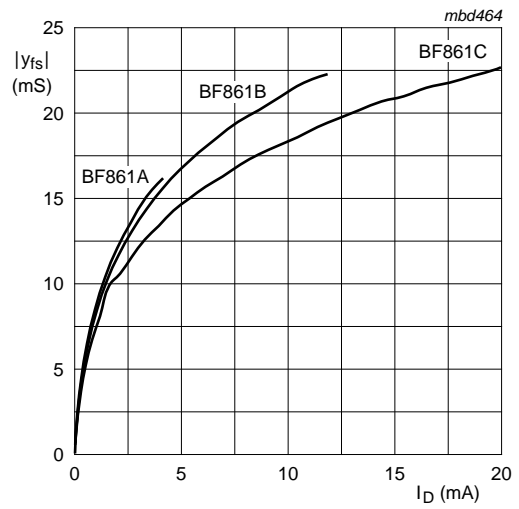
$V_{DS} = 8\text{ V}$.
 $V_{GS} = 0\text{ V}$.

Fig 3. Common-source output conductance as a function of drain current; typical values.



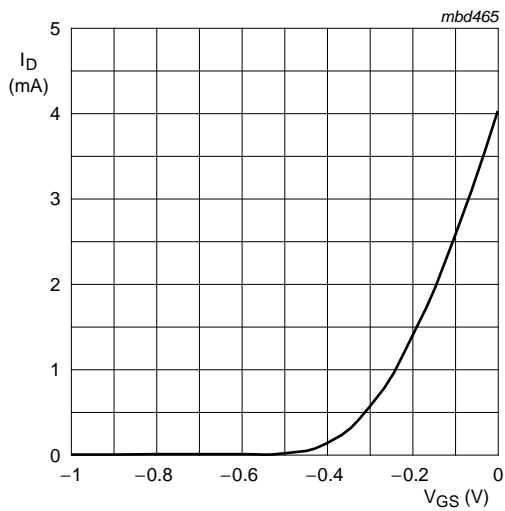
$V_{DS} = 8 \text{ V.}$
 $V_{GS} = 0 \text{ V.}$

Fig 4. Forward transfer admittance as a function of drain current; typical values.



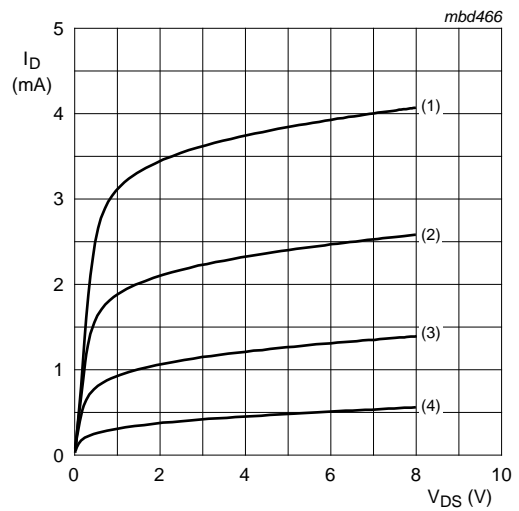
$V_{DS} = 8 \text{ V.}$

Fig 5. Forward transfer admittance as a function of drain current; typical values.



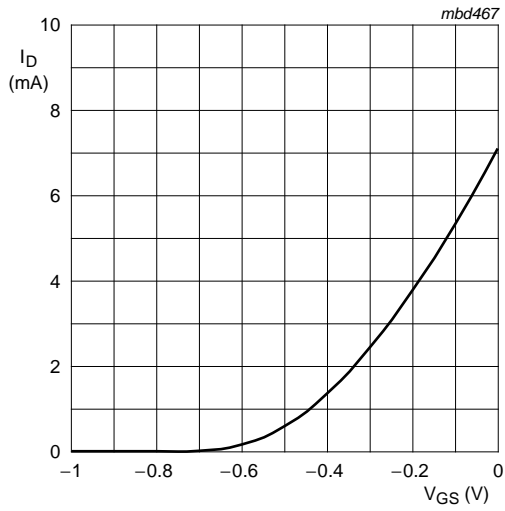
$V_{DS} = 8 \text{ V.}$

Fig 6. Typical input characteristics; BF861A.



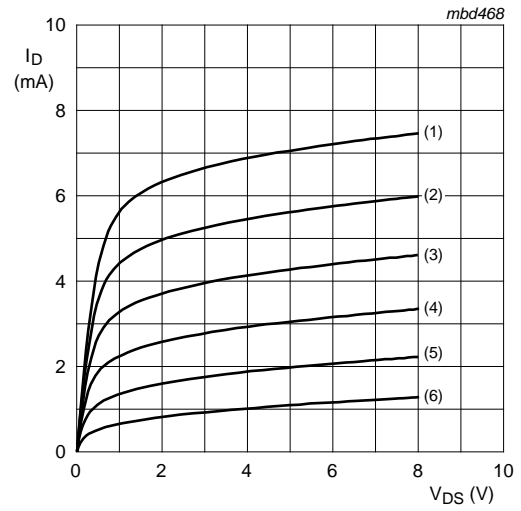
$V_{DS} = 8 \text{ V.}$
 (1) $V_{GS} = 0 \text{ V.}$
 (2) $V_{GS} = -100 \text{ mV.}$
 (3) $V_{GS} = -200 \text{ mV.}$
 (4) $V_{GS} = -300 \text{ mV.}$

Fig 7. Typical output characteristics: BF861A.



V_{DS} = 8 V.

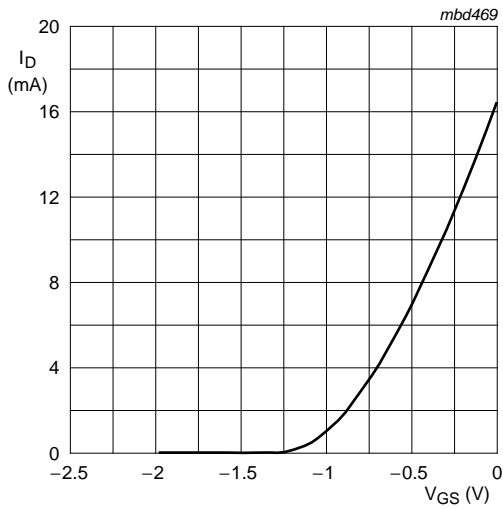
Fig 8. Typical input characteristics; BF861B.



V_{DS} = 8 V.

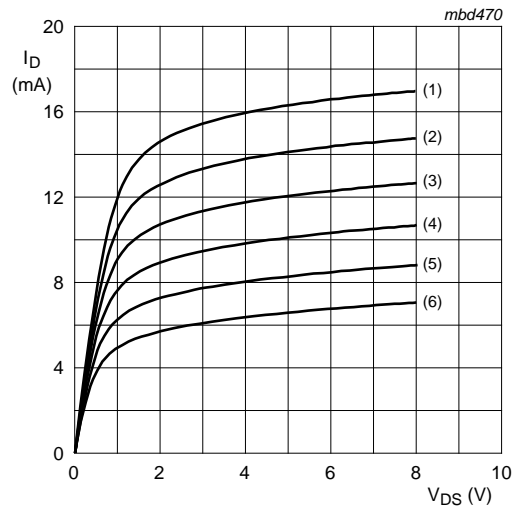
- (1) V_{GS} = 0 V.
- (2) V_{GS} = -100 mV.
- (3) V_{GS} = -200 mV.
- (4) V_{GS} = -300 mV.
- (5) V_{GS} = -400 mV.
- (6) V_{GS} = -500 mV.

Fig 9. Typical output characteristics; BF861B.



$V_{DS} = 8 \text{ V.}$

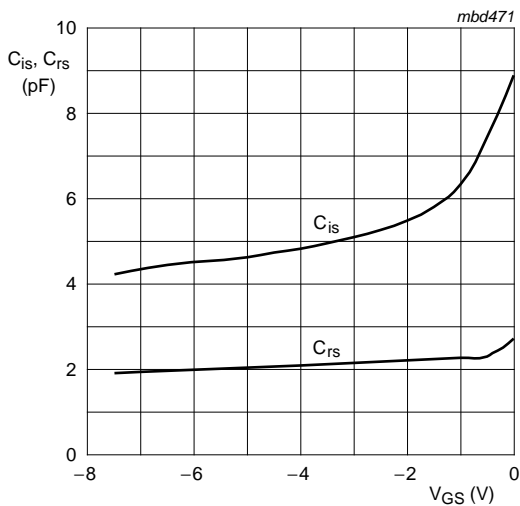
Fig 10. Typical input characteristics; BF861C.



$V_{DS} = 8 \text{ V.}$

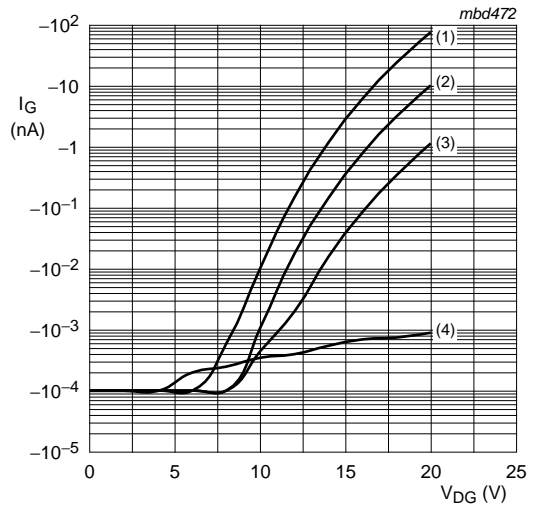
- (1) $V_{GS} = 0 \text{ V.}$
- (2) $V_{GS} = -200 \text{ mV.}$
- (3) $V_{GS} = -400 \text{ mV.}$
- (4) $V_{GS} = -600 \text{ mV.}$
- (5) $V_{GS} = -800 \text{ mV.}$
- (6) $V_{GS} = -1 \text{ V.}$

Fig 11. Typical output characteristics; BF861C.



$V_{DS} = 8 \text{ V.}$
 $f = 1 \text{ MHz.}$

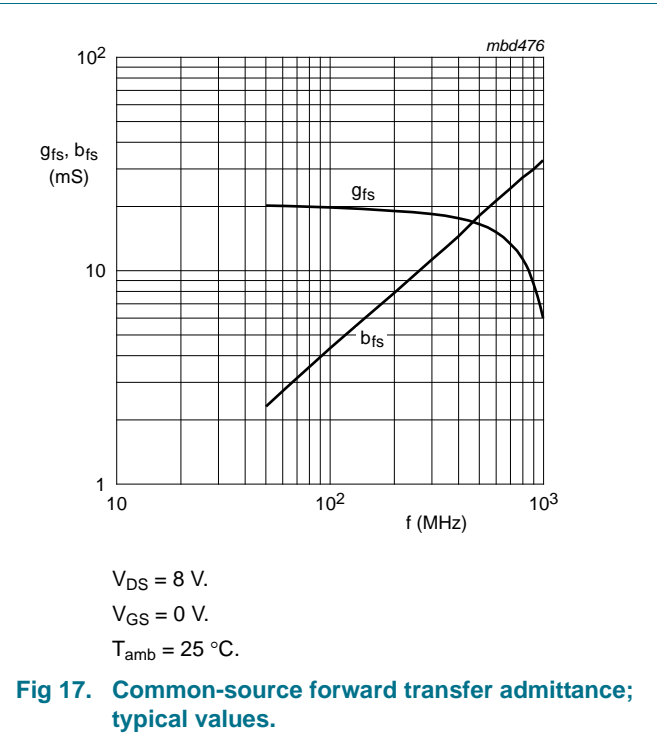
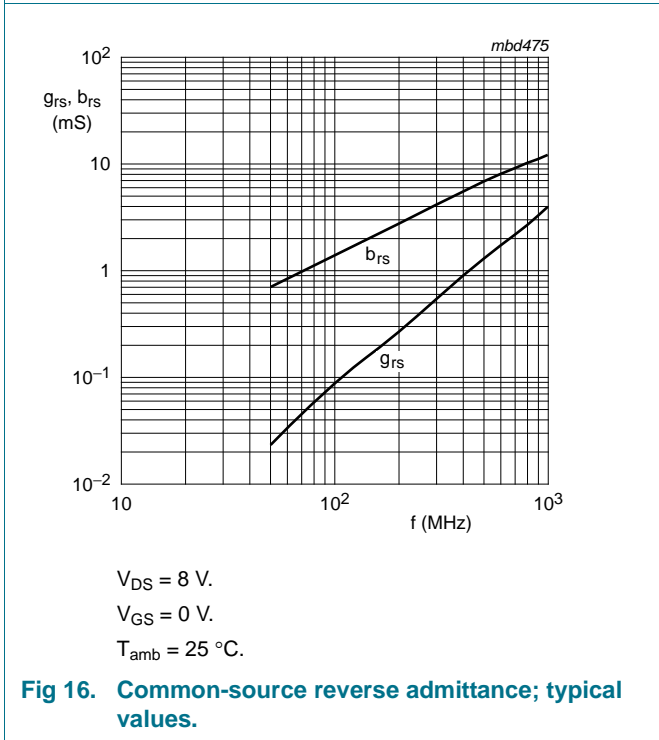
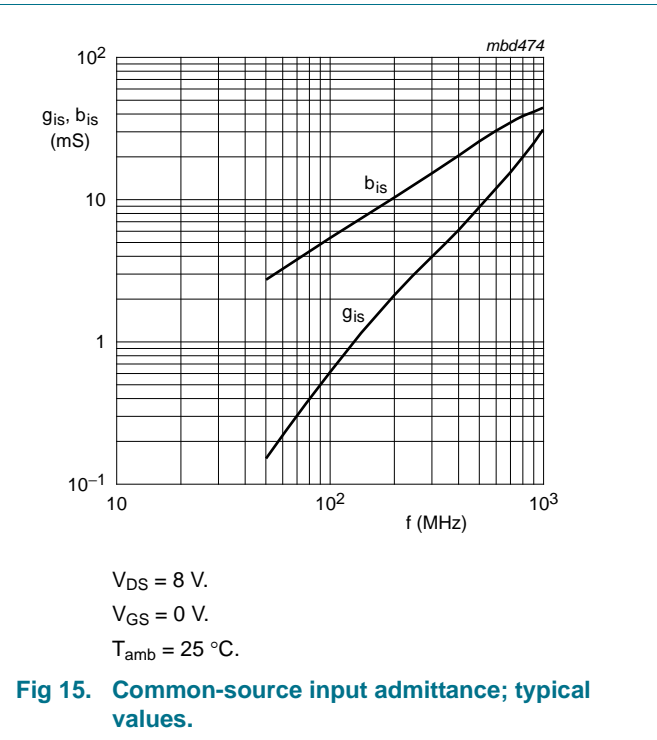
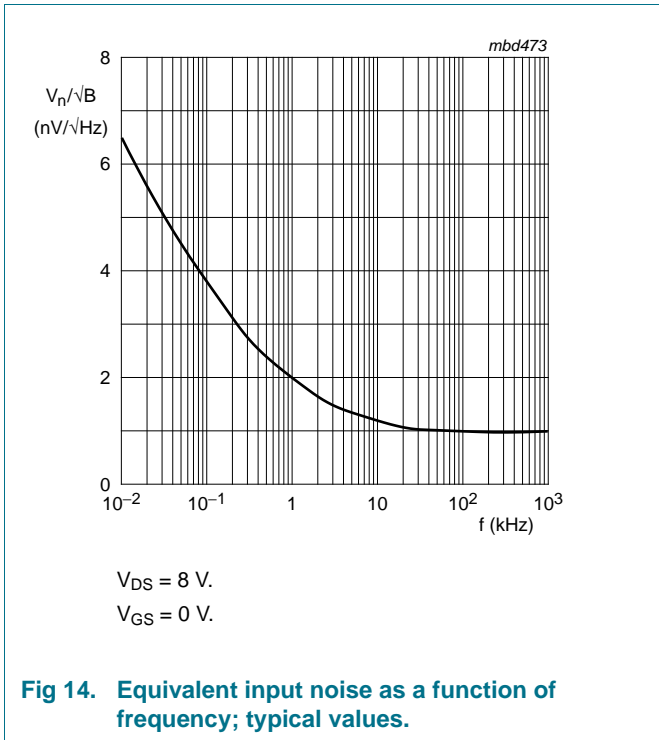
Fig 12. Input and reverse transfer capacitance as functions of gate-source voltage; typical values.

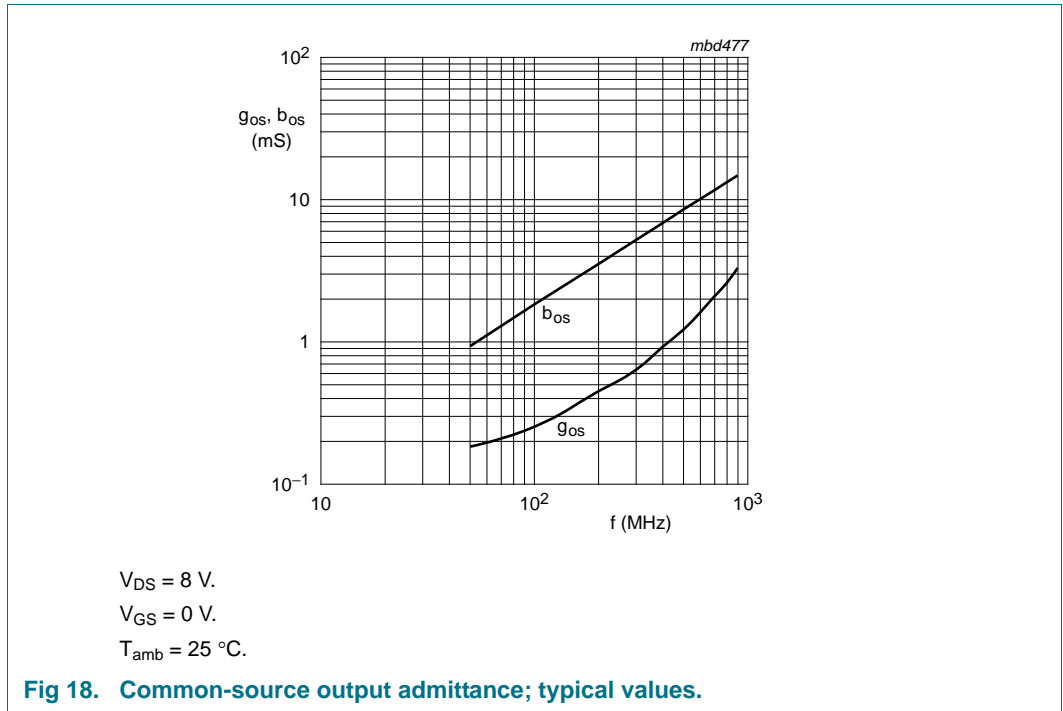


$V_{DS} = 8 \text{ V.}$

- (1) $I_D = 10 \text{ mA.}$
- (2) $I_D = 1 \text{ mA.}$
- (3) $I_D = 0.1 \text{ mA.}$
- (4) $I_D = I_{GSS}.$

Fig 13. Gate current as a function of drain-gate voltage; typical values.





8. Package outline

Plastic surface-mounted package; 3 leads

SOT23

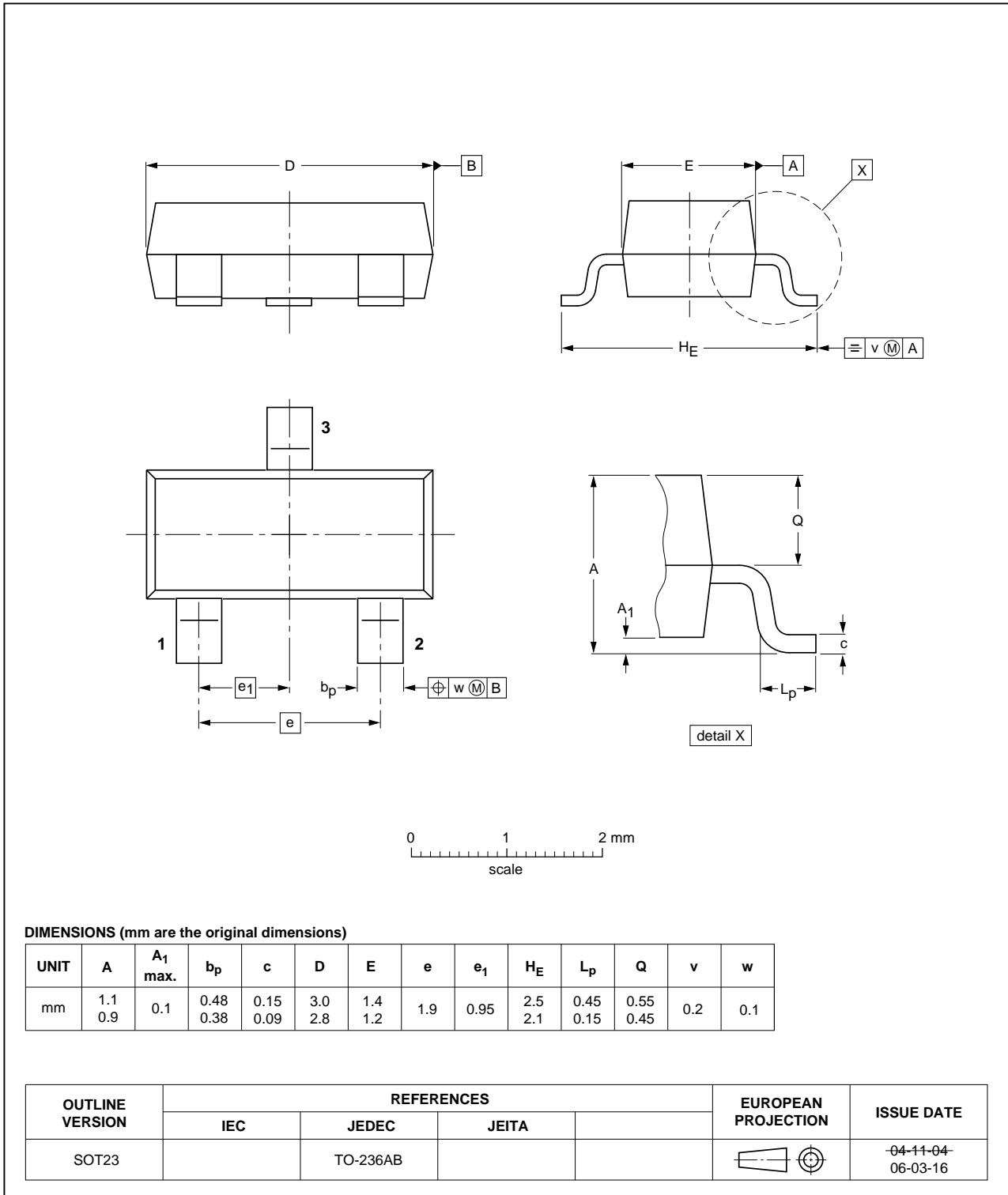


Fig 19. Package outline

9. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BF861A_BF861B_BF861C v.5	20110915	Product data sheet	-	BF861A_BF861B_BF861C v.4
Modifications:				
				<ul style="list-style-type: none"> • The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Package outline drawings have been updated to the latest version.
BF861A_BF861B_BF861C v.4 (9397 750 13395)	20040924	Product data sheet	-	BF861 v.3
BF861 v.3 (9397 750 02667)	19970904	Product specification	-	BF861 v.2
BF861 v.2	19950414	-	-	BF861 v.1
BF861 v.1	19940829	-	-	-

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9